HSMF-C113 and HSMF-C115

Right Angle Tricolor Surface Mount ChipLEDs



Data Sheet

Description

The HSMF-C113 / C115 tricolor chip-type LED is designed in an ultra small package for miniaturization. It is the first of its kind to achieve such small packaging for 3 dies. With the freedom to have any combination of colors from mixing of the 3 primary colors, this will yield a wide variety of colors to suit every application and product theme.

The small size, narrow footprint, and low profile make this LED excellent for back-lighting, status indication, and front panel illumination applications.

In order to facilitate pick and place operation, this ChipLED is shipped in tape and reel, with 3000 units per reel. The package is compatible with reflow soldering and binned by both color and intensity.

Features

- Common anode
- Small 2.5 x 1.0 x 1.0 mm package
- Diffused optics
- Available in 8 mm tape on 7" diameter reels
- High brightness using AllnGaP and InGaN die technology
- Compatible with reflow soldering

Applications

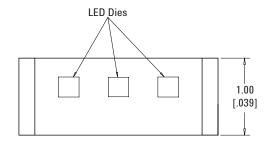
- Backlighting
- Status indicator
- Front panel indicator
- Office automation, home appliances, industrial equipment

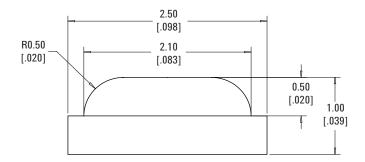
Device Selection Guide

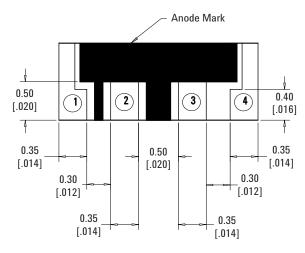
Part Number	Color	Package Description
HSMF-C113	AllnGaP Red / AllnGaP Green / InGaN Blue	Untinted, Diffused
HSMF-C115	AllnGaP Red / InGaN Green / InGaN Blue	Untinted, Diffused

CAUTION: HSMF-C113 and HSMF-C115 LEDs are Class 1A ESD sensitive per JESD22-A114C.01. Please observe appropriate precautions during handling and processing. Refer to Avago Technologies Application Note AN-1142 for additional details.

Package Dimensions







Notes:

- 1. All Dimensions in millimeteres (inches)
- 2. Tolerance is ± 0.1 mm (± 0.004 in) unless otherwise specified

POLARITY		HSMF-C113	HSMF-C115
		InGaN BLUE	InGaN BLUE
20-	3	AlinGaP RED	AllnGaP RED
	4	AlinGaP GREEN	InGaN GREEN

Absolute Maximum Ratings at T_A = 25°C

Parameter	AlinGaP Red	AllnGaP Green	InGaN Green	InGaN Blue	Units
DC Forward Current ^[1,3]	20	20	20	20	mA
Power Dissipation ^[1]	48	52	78	78	mW
DC Forward Current ^[2]	15	15	15	15	mA
Power Dissipation ^{[2}]	36	39	59	59	mW
Reverse Voltage (I _R = 100mA)	5	5	5	5	V
LED Junction Temperature	95	95	95	95	°C
Operating Temperature Range		-40 to	o +85		°C
Storage Temperature Range		-40 to	o +85		°C
Soldering Temperature	See IR soldering profile (Figure 6 & 7)				

Notes:

- 1. Applies when single LED is lit up.
- 2. Applies when all 3 LEDs are lit up simultaneously.
- 3. Derate linearly as shown in Figure 4.
- 4. Drive currents above 5 mA are recommended for best long term performance.

Electrical Characteristics at $T_A = 25$ °C

	VF (Ve	l Voltage olts) ^[1] : 20mA	Reverse Breakdown V _R (Volts) @ I _R = 100mA	Capacitance $C(pF)$, @ $V_F = 0$, $f = 1MHz$	Thermal Resistance $R\theta_{J-PIN}$ (°C/W)
Part Number	Тур.	Max.	Min.	Typ.	Typ.
AlinGaP Red	1.9	2.0	5	12	550
AllnGaP Green	2.0	2.6	5	15	300
InGaN Green	3.4	3.9	5	65	400
InGaN Blue	3.4	3.9	5	65	400

Notes:

1.Vf tolerance: ±0.1V

Optical Characteristics at $T_A = 25$ °C

	l _V [1]	us Intensity ¹ (mcd) 20mA	Peak Wavelength $\lambda_{ extsf{peak}}$ (nm)	Color, Dominant Wavelength $\lambda_{\mathbf{d}}^{[2]} \text{(nm)}$	Viewing Angle 20 _{1/2} ^[3] (Degrees)	Luminous Ef- ficacy ην (lm/W)
Part Number	Min.	Тур.	Typical	Typical	Typical	Typical
AllnGaP Red	28.5	80.0	637	626	120	155
AllnGaP Green	18.0	50.0	570	572	125	570
InGaN Green	71.5	170.0	523	525	125	443
InGaN Blue	28.5	60.0	468	470	125	89

Notes:

- 1. The luminous intensity I_V is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the LED package.
- 2. The dominant wavelength, λ_d , is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.
- 3. $\theta_{1/2}$ is the off-axis angle where the luminous intensity is ½ the peak intensity.

CAUTION:

- 1. The above optical performance specifications are valid in the case when single LED is lit up.
- 2. The above product specifications DO NOT provide any guarantee on color mixing, color consistency over time, or uniformity in luminous intensity when more than 1 LED is lit.
- Please refer to Avago Technologies Application Brief AB D-007 for additional details / explanation on driving the part in parallel circuit.

Light Intensity (I_V) Bin Limits^[1]

	Intensity (mcd)		
Bin ID	Minimum	Maximum	
Α	0.11	0.18	
В	0.18	0.29	
С	0.29	0.45	
D	0.45	0.72	
E	0.72	1.10	
F	1.10	1.80	
G	1.80	2.80	
Н	2.80	4.50	
J	4.50	7.20	
K	7.20	11.20	
L	11.20	18.00	
М	18.00	28.50	
N	28.50	45.00	
Р	45.00	71.50	
Q	71.50	112.50	
R	112.50	180.00	
S	180.00	285.00	
T	285.00	450.00	

Tolerance: ±15%

Notes:

 Bin categories are established for classifi-cation of products. Products may not be available in all categories. Please contact your Avago Technologies representative for information on current available bins.

AllnGaP Red Color Bin Limits[1]

	Dom. Wavelength (nm)	
Bin ID	Minimum	Maximum
	620.0	635.0

Tolerance: ±1nm

AllnGaP Green Color Bin Limits^[1]

	Dom. Wavelength (nm)		
Bin ID	Minimum	Maximum	
A	561.5	564.5	
В	564.5	567.5	
С	567.5	570.5	
D	570.5	573.5	
E	573.5	576.5	

Tolerance: ±1nm

InGaN Green Color Bin Limits[1]

	Dom. Wavelength (nm)		
Bin ID	Minimum	Maximum	
A	515.0	520.0	
В	520.0	525.0	
С	525.0	530.0	
D	530.0	535.0	

Tolerance: ±1nm

InGaN Blue Color Bin Limits^[1]

	Dom. Waveleng	th (nm)
Bin ID	Minimum	Maximum
A	460.0	465.0
В	465.0	470.0
С	470.0	475.0
D	475.0	480.0

Tolerance: ±1nm

Notes:

 Bin categories are established for classifi-cation of products. Products may not be available in all categories. Please contact your Avago Technologies representative for information on current available bins.

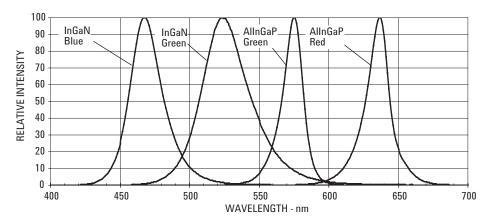


Figure 1. Relative intensity vs. wavelength.

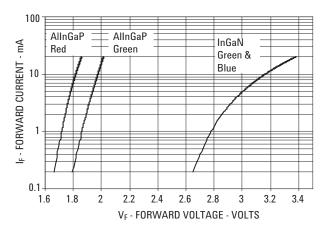


Figure 2. Forward current vs. forward voltage.

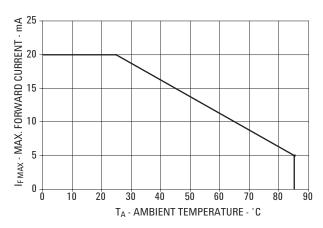


Figure 4. Maximum forward current vs. ambient temperature.

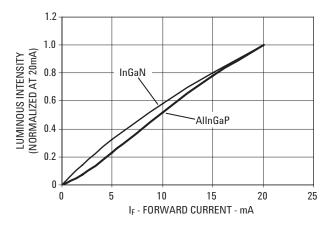


Figure 3. Luminous intensity vs. forward current.

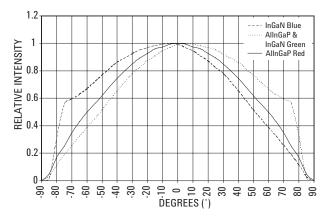


Figure 5. Relative intensity vs. angle.

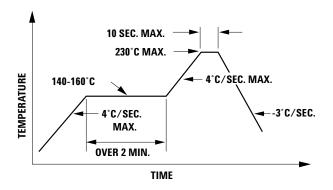


Figure 6. Recommended reflow soldering profile.

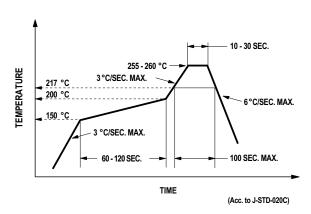


Figure 7. Recommended Pb-free reflow soldering profile.

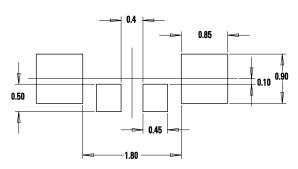
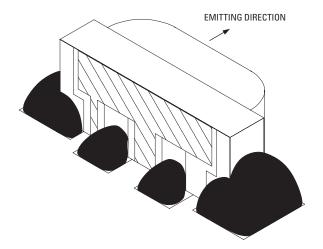


Figure 8. Recommended soldering land pattern.

Notes

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 mm$ ($\pm 0.004 in.$) unless otherwise specified.



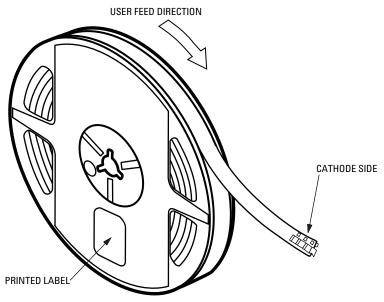


Figure 9. Reeling orientation.

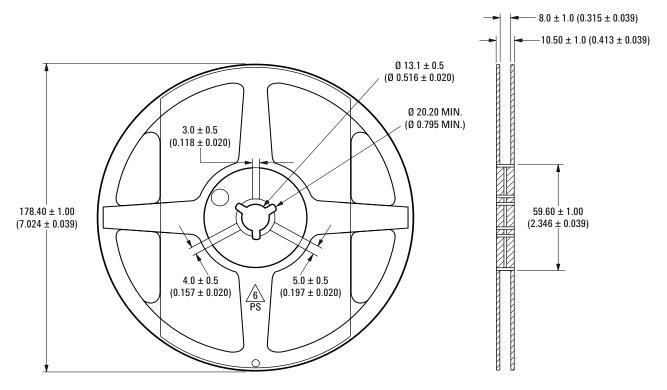
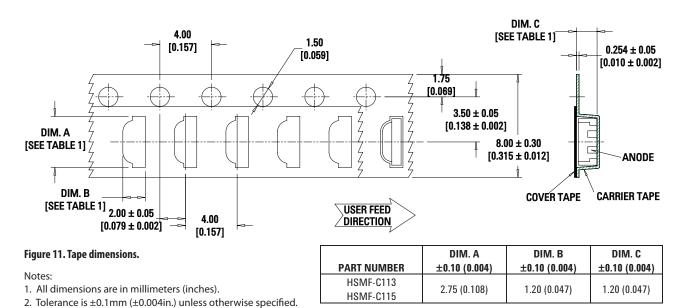


Figure 10. Reel dimensions.



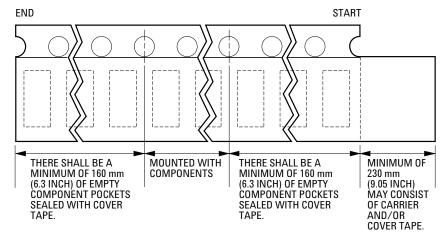


Figure 12. Tape leader and trailer dimensions.

Reflow Soldering:

For more information on reflow soldering, refer to Application Note AN-1060, Surface Mounting SMT LED Indicator Components.

Storage Condition: 5 to 30°C @ 60%RH max.

Baking is required before mounting, if:

- 1. Humidity Indicator Card is > 10% when read at 23 ± 5 °C.
- 2. Device expose to factory conditions <30°C/60%RH more than 672 hours.

Recommended baking condition: 60±5°C for 20 hours.



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Standard LEDs - SMD category:

Click to view products by Broadcom manufacturer:

Other Similar products are found below:

LTST-C19GD2WT LTST-N683GBEW LTW-170ZDC LTW-M140SZS40 598-8110-100F 598-8170-100F 598-8610-202F 67
22VRVGC/TR8 AAAF5060QBFSEEZGS HLMA-QG00-S0021 HLMP-6305-L0011 ALMD-LB36-SV002 APT1608QGW 15-21UYC/S530
A3/TR8 EASV1803BA0 LG M67K-H1J2-24-0-2-R18-Z LS A676-P2S1-1 SML-512VWT86A SML-LX0606SISUGC/A SML
LXL1307SRC-TR SML-LXR851SIUPGUBC LT1ED53A FAT801-S AM27ZGC03 APB3025SGNC APFA3010SURKCGKQBDC

APHK1608VGCA APT2012QGW CLX6D-FKB-CN1R1H1BB7D3D3 LTST-C250KGKT LTW-020ZDCG LTW-21TS5 LTW-220DS5

JANTXM19500/521-02 UYGT801-S 42-21UYC/S530-A3/TR8 LO T67F-V1AB-24-1 YGFR411-H SML-LX0402IC-TR

CMDA20AYAA7D1S CMDA16AYDR7A1X 339-1SURSYGW/S530-A2 598-8040-100F 598-8070-100F 598-8140-100F 598-8610-200F

EAPL3527GA5 SML-LXL1209SYC/ATR EASV3020YGA0 EAST16086YA5